

Development of Semiconductor Advanced Packaging Inspection Equipment(Holoway Inc.)



○ Business Plan

Leveraging proprietary digital holography technology, we are developing measurement and inspection solutions required for semiconductor advanced packaging—a field with high expectations for societal implementation in AI, autonomous driving, and the metaverse.

○ Research Outline

This research and development project aims to elevate our proprietary digital holography technology into a semiconductor measurement and inspection solution. By achieving high precision and high throughput, we seek to solve challenges in advanced semiconductor processes where further innovation and QCD improvement are required.

City	Year of Establishment	Founder
Kobe	2023	Kunihiro Sato

Partner VC	Latest round of Fundraising	Valuation
Globis Capital Partners	Series A	JPY 2,635 million

Business Area/Field	Research Period	Research Grant Amount	International collaborative technology demonstration
Information & Communication	STS 2025-2027FY	JPY 292 million	Asia, United States, Europe etc.

Contact Information : Non-Disclosure

Website : <https://holoway.co.jp>